

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Previously Presented) A back electrode electronic part comprising:

a main body;

a circuit; and

electrodes arranged on an outer back surface of the main body; wherein:

the electrodes comprise integration possible electrodes and general electrodes;

a plurality of the integration possible electrodes are arranged adjacently to each other to form a group of integration possible electrodes;

the group of integration possible electrodes is connected to a single first solder bump;

each of the general electrodes are individually connected to single second solder bumps;

the first solder bump is larger than each of the second solder bumps; and

each of the integration possible electrodes that are part of the group of integration possible electrodes have a substantially same potential level when said circuit operates.

2. (Previously Presented) A back electrode electronic part according to claim 1, wherein said electrodes are arranged in a matrix, and said group of integration possible electrodes is arranged at a corner of the matrix.

3. (Previously Presented) A back electrode electronic part according to claim 1, wherein one of the integration possible electrodes that are part of said group of integration possible electrodes comprises a non-contact electrode which is not connected to said circuit.

4. (Previously Presented) A back electrode electronic part according to claim 1, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a signal electrode.

5. (Previously Presented) A back electrode electronic part according to claim 1, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a ground potential electrode.

6. (Previously Presented) A back electrode electronic part according to claim 1, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a power supply potential electrode.

7. (Previously Presented) An electronic assembly comprising:

a back electrode electronic part comprising:

a main body;

a circuit, and

electrodes arranged on an outer back surface of the main body, wherein:
the electrodes comprise integration possible electrodes and general electrodes;
a plurality of the integration possible electrodes are arranged adjacently to each other to form a group of integration possible electrodes;
each of the integration possible electrodes that are part of the group of integration possible electrodes have a substantially same potential level when said circuit operates,
said electronic assembly further comprising:
a printed circuit board; and
substrate electrodes arranged on an outer surface of the printed circuit board, wherein:
the substrate electrodes comprising a first substrate electrode and second substrate electrodes;
said group of integration possible electrodes and said first substrate electrode are connected to a single first solder bump;
each of said general electrodes and each of said second substrate electrodes are individually connected to single second solder bumps; and
said first solder bump is larger than each of the second solder bumps.

8. (Currently Amended) ~~A back electrode electronic part~~ An electronic assembly according to claim 7, wherein said electrodes of said back electrode electronic part are arranged in a matrix, and said group of integration possible electrodes is arranged at a corner of the matrix.

9. (Previously Presented) An electronic assembly according to claim 7, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a non-contact electrode which is not connected to said circuit.

10. (Previously Presented) An electronic assembly according to claim 7, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a signal electrode.

11. (Previously Presented) An electronic assembly according to claim 7, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a ground potential electrode.

12. (Previously Presented) An electronic assembly part according to claim 7, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a power supply potential electrode.

13. (Previously Presented) A back electrode electronic part according to claim 1, wherein said group of integration possible electrodes is directly connected to said first solder bump.

14. (Previously Presented) A back electrode electronic part according to claim 1, wherein said electrodes arranged on an outer surface of the main body of the back electrode electronic part protrude from said back electrode electronic part so as to support said first and second solder bumps.

15. (Previously Presented) A back electrode electronic part according to claim 1, wherein the outer surface of the main body is a rearmost surface of said back electrode electronic part.

16. (Previously Presented) An electronic assembly according to claim 7, wherein said group of integration possible electrodes are directly connected to said first solder bump.

17. (Previously Presented) An electronic assembly according to claim 7, wherein said electrodes arranged on an outer surface of the main body of the back electrode electronic part protrude from said back electrode electronic part so as to support said first and second solder bumps.

18. (Previously Presented) An electronic assembly according to claim 7, wherein the outer surface of the main body is a rearmost surface of said back electrode electronic part.

19. (Currently Amended) A back electrode electronic part comprising:

at least two first electrodes positioned on an outer rear surface of said electronic part and connected to a first solder bump;

at least one second electrode positioned on the outer rear surface of said electronic part and connected to a second solder bump, wherein

said first solder bump has a larger lateral cross section than said second solder bump; and
each of said first electrodes and second electrode are arranged in a matrix on said rear surface of said electronic part so that the first electrodes are spaced apart by the same distance that the second electrode is spaced apart from a nearest one of the first electrodes.

20. (Cancelled)

21. (Previously Presented) A back electrode electronic part comprising:
a main body including a circuit; and
electrodes arranged for solder bumps and supported on an outer back surface portion of said electronic part and connected to said circuit; wherein

said electrodes are arranged into groups of electrodes at portions of the electrode arrangement;

at least one of said groups of electrodes is connected to a first solder bump which is larger than second solder bumps connected to said electrodes arranged other than in said groups of electrodes;

the electrodes arranged other than in said groups of electrodes are each connected to only one second solder bump; and

said groups of electrodes include electrodes having a substantially same potential level when said circuit operates.

22. (Cancelled)

23. (Previously Presented) A back electrode electronic part according to claim 1, wherein each of the electrodes are the same size.

24. (Currently Amended) A back electrode electronic part according to claim 1, wherein a first distance between a first and a second one of the plurality of integration electrodes forming the group of integration possible electrodes is the same as a second distance between the first one of the plurality of integration electrodes and a nearest one of the general electrodes.

25. (Previously Presented) A back electrode electronic part according to claim 1, wherein four integration electrodes form the group of integration possible electrodes.

26. (Previously Presented) A back electrode electronic part according to claim 1, wherein three integration electrodes form the group of integration possible electrodes.

27. (Previously Presented) A back electrode electronic part according to claim 1, wherein a first and second one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a ground electrode and a non-contact electrode, respectively.

28. (Previously Presented) A back electrode electronic part according to claim 1, wherein a first and second one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a signal electrode and a non-contact electrode, respectively.

29. (Previously Presented) A back electrode electronic part according to claim 1, wherein a first and second one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a power electrode and a non-contact electrode, respectively.

30. (Previously Presented) An electronic assembly according to claim 7, wherein each of the electrodes of the back electrode electronic part are the same size.

31. (Currently Amended) An electronic assembly according to claim 7, wherein a first distance between a first and a second one of the plurality of integration electrodes of the back electrode electronic part forming the group of integration possible electrodes is the same as a

second distance between the first one of the plurality of integration electrodes and a nearest one of the general electrodes.

32. (Previously Presented) An electronic assembly according to claim 7, wherein four integration electrodes of the back electrode electronic part form the group of integration possible electrodes.

33. (Previously Presented) An electronic assembly according to claim 7, wherein three integration electrodes of the back electrode electronic part form the group of integration possible electrodes.

34. (Previously Presented) An electronic assembly according to claim 7, wherein a first and second one of said integration possible electrodes of the back electrode electronic part that are part of said group of integration possible electrodes comprises a ground electrode and a non-contact electrode, respectively.

35. (Previously Presented) An electronic assembly according to claim 7, wherein a first and second one of said integration possible electrodes of the back electrode electronic part that are part of said group of integration possible electrodes comprises a signal electrode and a non-contact electrode, respectively.

36. (Previously Presented) An electronic assembly according to claim 7, wherein a first and second one of said integration possible electrodes of the back electrode electronic part that are part of said group of integration possible electrodes comprises a power electrode and a non-contact electrode, respectively.

37. (New) An electronic assembly according to claim 7, wherein said first substrate electrode of said printed circuit board is larger than each of said second electrodes of said printed circuit board.